



Material Content Data Sheet



Sales Product Name		TLE8386EL		Issued		26. September 2017		
MA#		MA000971506						
Package		PG-SSOP-14-3		Weight*		83.06 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.030	2.44	2.44	24439	24439
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.689	0.83		8296	
wire	non noble metal	copper	7440-50-8	27.978	33.68	34.56	336844	345659
	noble metal	gold	7440-57-5	0.199	0.24	0.24	2395	2395
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1196
encapsulation	plastics	epoxy resin	-	4.570	5.50		55017	
	inorganic material	silicondioxide	60676-86-0	45.001	54.19	59.81	541799	598012
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11752	11752
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9242	9242
glue	plastics	epoxy resin	-	0.177	0.21		2125	
	noble metal	silver	7440-22-4	0.530	0.64	0.85	6376	8501
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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